



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20230814006.1**

**Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, Datasheet and additional Assembly site/BOM options for select devices  
Change Notification / Sample Request**

**Date:** August 14, 2023  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team  
SC Business Services

**20230814006.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AM26LV32EIDR	null
AM26LV32EIPWR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20230814006.1	<b>PCN Date:</b>	August 14, 2023
<b>Title:</b>	Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, Datasheet and additional Assembly site/BOM options for select devices		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Nov 14, 2023	<b>Sample requests accepted until:</b>	Sep 14, 2023*

**\*Sample requests received after September 14, 2023 will not be supported.**

Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

## PCN Details

### Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9) and additional Assembly site (CDAT, MLA) for selected devices listed below in the product affected section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DL-LIN	LBC3S	150 mm	RFAB	LBC9	300mm
SFAB	J12	150 mm			
SFAB	IMP-C60	150 mm			

Construction differences are as follows (There are no construction differences for Group 1 and Group 3 devices):

### Group 2 BOM Table (Process migration & BOM option qualification):

	Current	New
Bond wire diameter (Cu)	0.96 mil	0.8 mil and 1 mil

### Group 4 BOM Table (Process migration & CDAT as an additional Assembly site):

	MLA	CDAT
Bond wire diameter (Cu)	0.96 mil	0.8 mil
Mold Compound	4208625	4222198
Mount Compound	4205846	4207123

The die was also changed as a result of the process change.

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



AM26LS32AC, AM26LS32AI, AM26LS32AM  
AM26LS33AC, AM26LS33AM  
SLLS115G – OCTOBER 1980 – REVISED AUGUST 2023

### Changes from Revision F (August 2016) to Revision G (August 2023)

Page

- Changed the Device Information table to the *Package Information* table..... 1
- Changed the *Thermal Information* table..... 5
- Changed the *Typical Characteristics* ..... 8

**Changes from Revision D (December 2020) to Revision E (August 2023)**
**Page**

- Changed the Device Information table to the *Package Information* table..... **1**
- Changed the *Thermal Information* ..... **5**
- Changed the *Typical Characteristics* ..... **6**

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
AM26LS32AC, AM26LS32A	<b>SLLS115F</b>	<b>SLLS115G</b>	<a href="http://www.ti.com/product/AM26LS32AC">http://www.ti.com/product/AM26LS32AC</a>
AM26LV32E	<b>SLLS849D</b>	<b>SLLS849E</b>	<a href="http://www.ti.com/product/AM26LV32E">http://www.ti.com/product/AM26LV32E</a>

Qual details are provided in the Qual Data Section.

**Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-millimeter and 200-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings:**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

**Changes to product identification resulting from this PCN:**
**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
SH-BIP-1	SHE	USA	Sherman
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

**Die Rev:**
**Current**
**New**

Die Rev [2P]	Die Rev [2P]
A, C, -	-

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
FMX	MEX	MEX	Aguascalientes
<b>MLA</b>	<b>MLA</b>	<b>MYS</b>	<b>Kuala Lumpur</b>
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)



#### Product Affected:

#### Group 1 Device list: (Process migration & MLA as an additional Assembly site)

AM26LS32AIDR	AM26LS32AIDRG4	AM26LS33ACDR	AM26LV32IDR
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#### Group 2 Device list: (Process migration & BOM option qualification)

AM26LS32ACDR	AM26LS32ACDRE4
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#### Group 3 Device list: (Process migration only)

AM26LS32ACN	AM26LS32ACPWR	AM26LV32EIDRG4	AM26LV32EIPWRG4
AM26LS32ACNSR	AM26LS32ACPWRE4	AM26LV32EINSR	AM26LV32INSR
AM26LS32ACNSRG4	AM26LV32EIDR	AM26LV32EIPWR	

#### Group 4 Device list: (Process migration & CDAT as an additional Assembly site)

AM26LV32EIRGYR	AM26LV32EIRGYRG4
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AM26LS32ACN	Qual Device: AM26LS32AIDR	Qual Device: AM26LS32ACNSR	Qual Device: AM26LS32ACPWR	QBS Reference (Package): TMUX1108PWR	QBS Reference (Package): TMUX1208PWR	QBS Reference (Process): TLV9062ID	QBS Reference (Package): ADS900E	QBS Reference (Package): SN74LVC8T249NSR
UHASt	A3	Autoclave	121C, 2 atm	96 Hours	-	-	-	-	2/154/0	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	2/154/0	1/77/0	-	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	2/154/0	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	3/2400/1 <sup>1</sup>	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	-	-	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JEDEC78	-	-	1/3/0	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Min. Typ. Max Temp	-	-	1/30/0	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-	-	-	-	-	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	1/1/0	1/1/0	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device AM26LS32ACN is not classified
- Qual Device AM26LS32AIDR is qualified at MSL1 260C
- Qual Device AM26LS32ACNSR is qualified at MSL1 260C
- Qual Device AM26LS32ACPWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2205-023

[1]-Die EOS

1 unit – discounted

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AM26LV32EIDR	Qual Device: AM26LV32EINSR	Qual Device: AM26LV32EIPWR	QBS Reference (Package): TMUX1168PWR	QBS Reference (Package): TMUX1208PWR	QBS Reference (Process): TLV9062ID	QBS Reference (Package): ULQ2003AQDRQ1	QBS Reference (Package): SN74LVC8T245NSR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C, 2 atm	96 Hours	-	-	-	2/154/0	1/77/0	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C	96 Hours	-	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	2/154/0	1/77/0	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	2/154/0	1/77/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	3/2400/1 <sup>1</sup>	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	1/76/0	-	-	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	1/76/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">AM26LV32EIDR</a>	Qual Device: <a href="#">AM26LV32EINSR</a>	Qual Device: <a href="#">AM26LV32EIPWR</a>	QBS Reference (Package): <a href="#">TMUX1168PWR</a>	QBS Reference (Package): <a href="#">TMUX1208PWR</a>	QBS Reference (Process): <a href="#">TLV9062ID</a>	QBS Reference (Package): <a href="#">ULQ2003AQDRQ1</a>	QBS Reference (Package): <a href="#">SN74LVC8T245NSR</a>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	2000 Volts	-	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	5000 Volts	-	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/6/0	1/6/0	-	-	-
CHAR	E5	Electrical Characterization	Min. Typ. Max Temp	-	1/30/0	-	-	1/30/0	1/30/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	3/90/0	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	1/1/0	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device AM26LV32EIDR is qualified at MSL1 260C
- Qual Device AM26LV32EINSR is qualified at MSL1 260C
- Qual Device AM26LV32EIPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2205-031

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">AM26LV32EIRGYR</a>	QBS Reference (Process): <a href="#">TLV9062ID</a>	QBS Reference (Package): <a href="#">TS3A5017QRGYRQ1</a>	QBS Reference (Package): <a href="#">TPS3850G09ADRCR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C	96 Hours	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	750 Cycles	-	-	-	1/30/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/1 <sup>1</sup>	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <u>AM26LV32EIRGYR</u>	QBS Reference (Process): <u>TLV9062ID</u>	QBS Reference (Package): <u>TS3A5017QRGYRQ1</u>	QBS Reference (Package): <u>TPS3850G09ADRCR</u>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
FTY	E6	Final Test Yield	-	-	1/1/0	-	-	-

- QBS: Qual By Similarity
- Qual Device AM26LV32EIRGYR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2205-035

[1]-Die EOS  
1 unit – discounted

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>AM26LV32IDR</u>	Qual Device: <u>AM26LV32INSR</u>	QBS Reference (Process): <u>TLV9062ID</u>	QBS Reference (Package): <u>ADS900E</u>	QBS Reference (Package): <u>PCM1801U</u>	QBS Reference (Package): <u>TCA9546ADR</u>	QBS Reference (Package): <u>SN74LVC8T245NSR</u>
UHAIST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	1/77/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0	3/231/0	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/1 <sup>1</sup>	-	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	-	-	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	3/66/0	-	-	3/66/0	-



Type	#	Test Name	Condition	Duration	Qual Device: AM26LV32IDR	Qual Device: AM26LV32INSR	QBS Reference (Process): TLV9062ID	QBS Reference (Package): ADS900E	QBS Reference (Package): PCM1801U	QBS Reference (Package): TCA9546ADR	QBS Reference (Package): SN74LVC8T245NSR
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device AM26LV32IDR is qualified at MSL1 260C
- Qual Device AM26LV32INSR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2205-030

[1]-Die EOS  
1 unit – discounted

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AM26LS32ACDR	QBS Reference (Process): TLV9062ID	QBS Reference (Package): PCM1801U	QBS Reference (Package): TL494IDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/1 <sup>1</sup>	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	3/66/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	3/9/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	3/18/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	3/90/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: AM26LS32ACDR	QBS Reference (Process): TLV9062ID	QBS Reference (Package): PCM1801U	QBS Reference (Package): TL494IDR
FTY	E6	Final Test Yield	-	-	1/1/0	-	-	-

- QBS: Qual By Similarity
- Qual Device AM26LS32ACDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2205-024

[1]-Die EOS  
1 unit – discounted

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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